



Parameter	Rating	Units
Blocking Voltage	350	V_P
Load Current	100	mA_{rms} / mA_{DC}
On-Resistance (max)	35	Ω

Features

- 3750V_{rms} Input/Output Isolation
- Three Functions in One Package
- Bidirectional Current Sensing
- Bidirectional Current Switching
- FCC Compatible
- No EMI/RFI Generation
- Small 16-Pin SOIC Package (PCMCIA Compatible)
- Machine Insertable, Wave Solderable
- Tape & Reel Versions Available

Applications

- Telecommunications
 - Telecom Switching
 - Tip/Ring Circuits
 - Modem Switching (Laptop, Notebook, Pocket Size)
 - Hook Switch
 - Dial Pulsing
 - Ground Start
 - Ringer Injection
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

The IAB110P Multifunction Telecom switch combines one 350V single-pole, normally open (1-Form-A) relay; one 350V single-pole, normally closed (1-Form-B) relay; and one bidirectional optocoupler in a single package. Optically coupled relay outputs that use the patented OptoMOS architecture are controlled by a highly efficient GaAIAs infrared LED.

The IAB110P allows telecom circuit designers to combine three discrete functions in a single component, whose small package uses less space than traditional discrete component solutions.

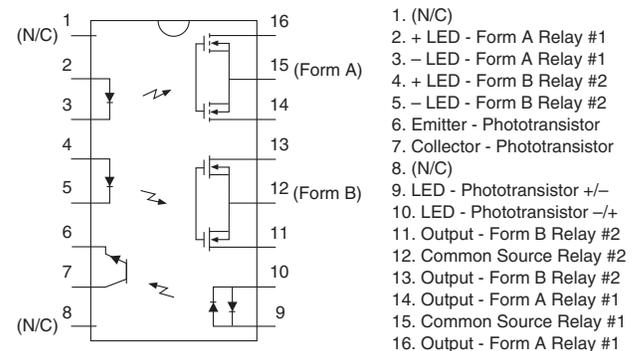
Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1305490
- EN/IEC 60950-1 Certified Component:
TUV Certificate: B 12 11 82667 002

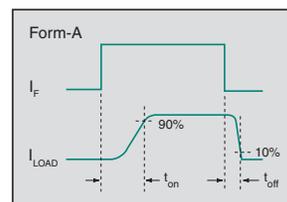
Ordering Information

Part #	Description
IAB110P	16-Pin SOIC (50/Tube)
IAB110PTR	16-Pin SOIC (1000/Reel)

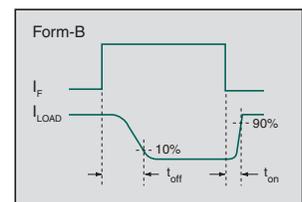
Pin Configuration



Switching Characteristics of Normally Open Devices



Switching Characteristics of Normally Closed Devices



Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Input Control Current, Relay	50	mA
Total Package Dissipation ¹	1	W
Isolation Voltage, Input to Output	3750	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 1.67 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Electrical Characteristics @25°C: Relay Section

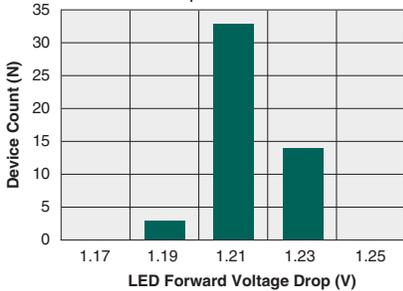
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Blocking Voltage (Peak)	I _L =1μA	V _L	-	-	350	V _p
Load Current						
Continuous	-	I _L	-	-	100	mA _{rms} / mA _{DC}
Peak	t=10ms	I _{LPK}	-	-	350	mA _p
On-Resistance	I _L =100mA	R _{ON}	-	-	35	Ω
Off-State Leakage Current	V _L =350V, T _j =25°C	I _{LEAK}	-	-	1	μA
Switching Speeds						
Turn-On	I _F =5mA, V _L =10V	t _{on}	-	-	3	ms
Turn-Off		t _{off}	-	-	3	ms
Output Capacitance	V _L =50V, f=1MHz	C _{OUT}	-	25	-	pF
Input Characteristics						
Input Control Current to Activate	I _L =100mA	I _F	-	-	5	mA
Input Control Current to Deactivate	I _L =1mA	I _F	0.4	-	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Reverse Input Voltage	-	V _R	-	-	5	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA

Electrical Characteristics @25°C: Detector Section

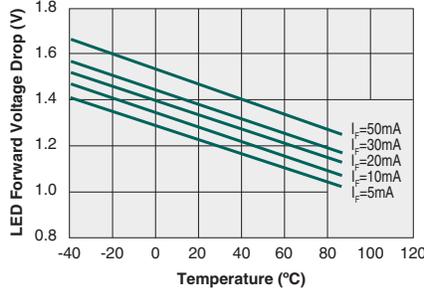
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Phototransistor Blocking Voltage	I _C =10μA	BV _{CEO}	20	50	-	V
Phototransistor Dark Current	V _{CE} =5V, I _F =0mA	I _{CEO}	-	50	500	nA
Saturation Voltage	I _C =2mA, I _F =16mA	V _{SAT}	-	0.3	0.5	V
Current Transfer Ratio	I _F =6mA, V _{CE} =0.5V	CTR	33	-	-	%
Input Characteristics						
Input Control Current	I _C =2mA, V _{CE} =0.5V	I _F	-	2	6	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Input Current (Detector Must be Off)	I _C =1μA, V _{CE} =5V	-	5	25	-	μA
Capacitance, Input to Output	V _L =50V, f=1MHz	C _{I/O}	-	3	-	pF
Isolation, Input to Output	-	V _{I/O}	3750	-	-	V _{rms}

DEVICE PERFORMANCE DATA*

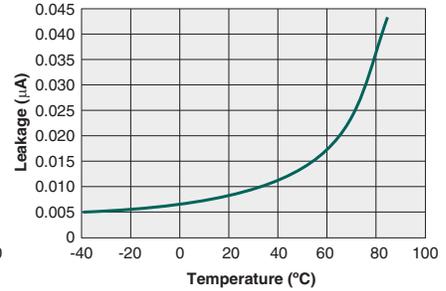
Typical LED Forward Voltage Drop
(N=50, $I_F=5mA$, $T_A=25^\circ C$)



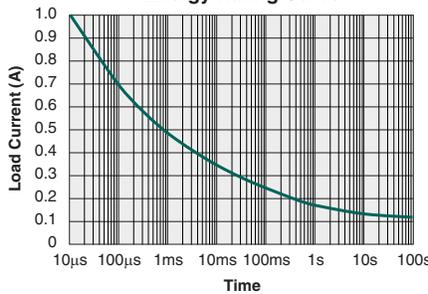
Typical LED Forward Voltage Drop vs. Temperature



Typical Leakage vs. Temperature
Measured Across Pins 14&16 or 11&13

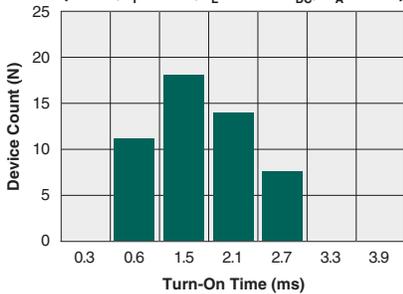


Energy Rating Curve

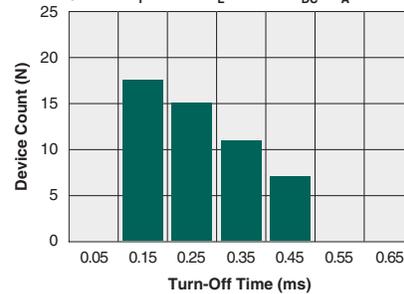


1-FORM-A RELAY PERFORMANCE DATA*

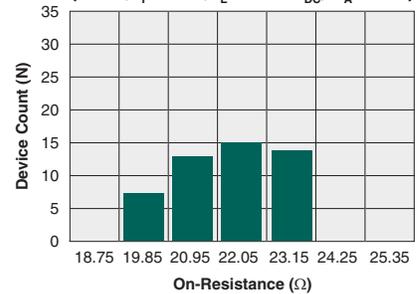
1-Form-A
Typical Turn-On Time
(N=50, $I_F=5mA$, $I_L=100mA_{DC}$, $T_A=25^\circ C$)



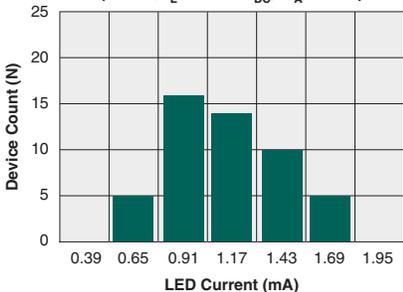
1-Form-A
Typical Turn-Off Time
(N=50, $I_F=5mA$, $I_L=100mA_{DC}$, $T_A=25^\circ C$)



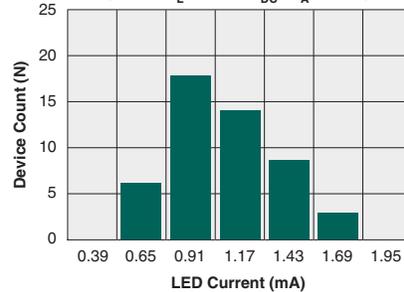
1-Form-A
Typical On-Resistance Distribution
(N=50, $I_F=5mA$, $I_L=100mA_{DC}$, $T_A=25^\circ C$)



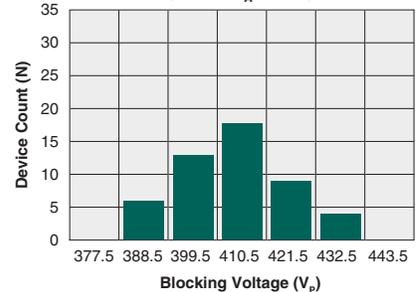
1-Form-A
Typical I_F for Switch Operation
(N=50, $I_L=100mA_{DC}$, $T_A=25^\circ C$)



1-Form-A
Typical I_F for Switch Dropout
(N=50, $I_L=100mA_{DC}$, $T_A=25^\circ C$)

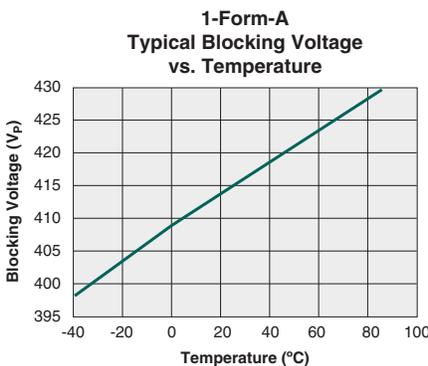
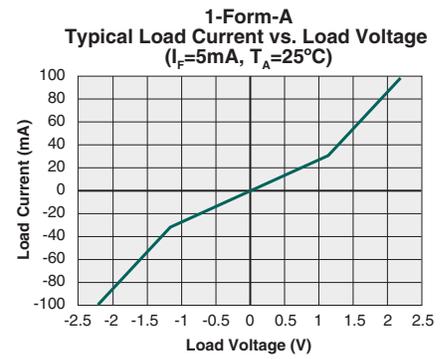
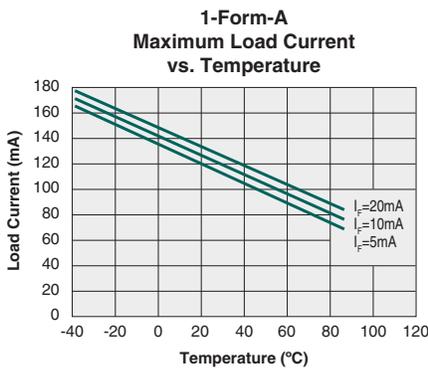
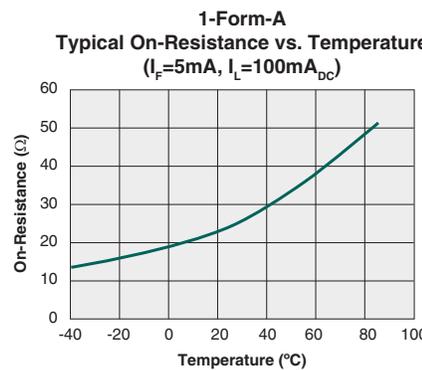
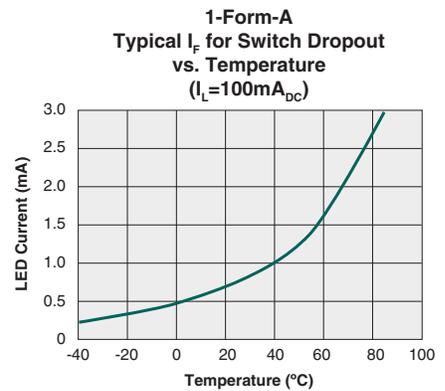
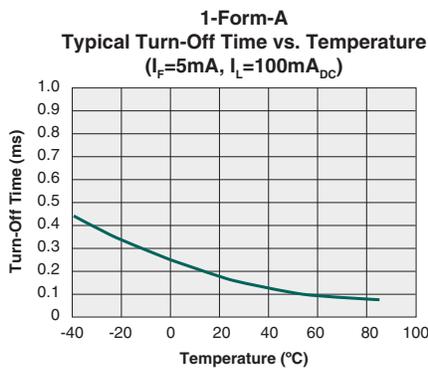
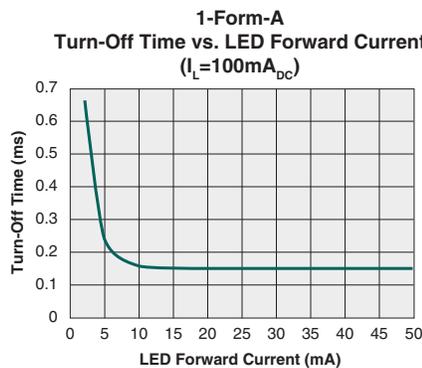
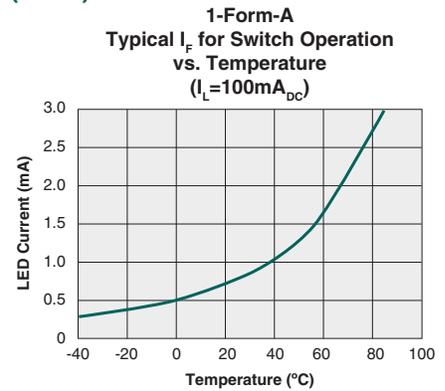
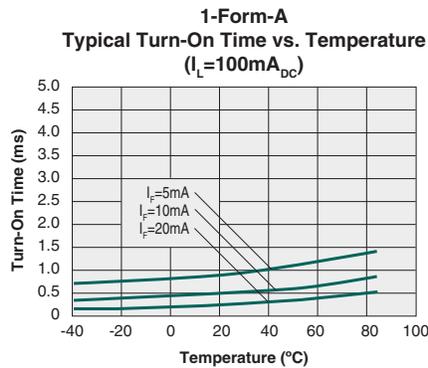
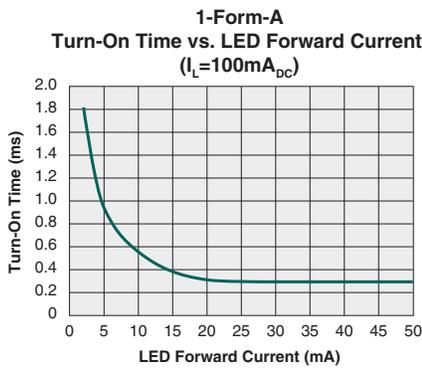


1-Form-A
Typical Blocking Voltage Distribution
(N=50, $T_A=25^\circ C$)



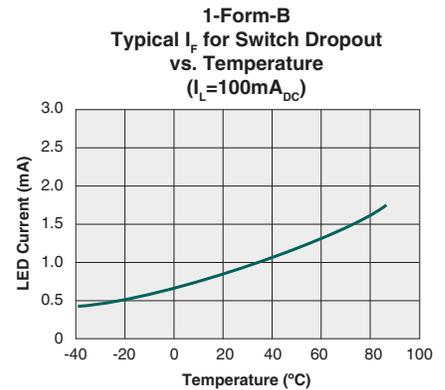
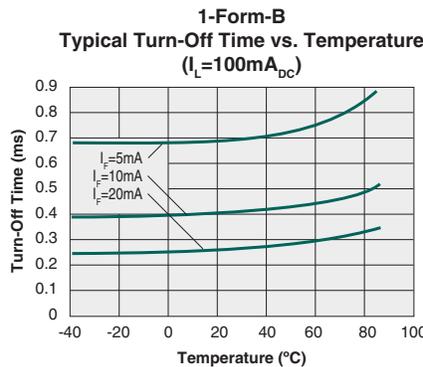
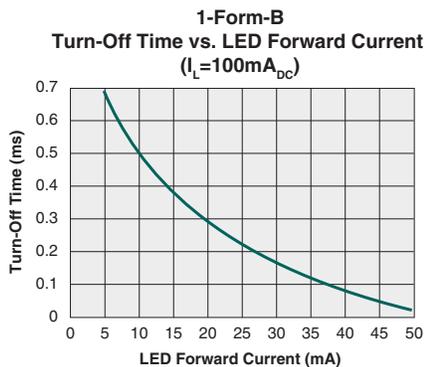
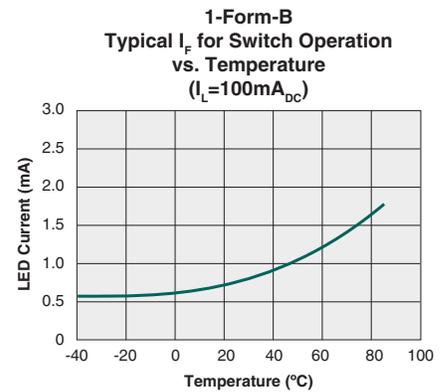
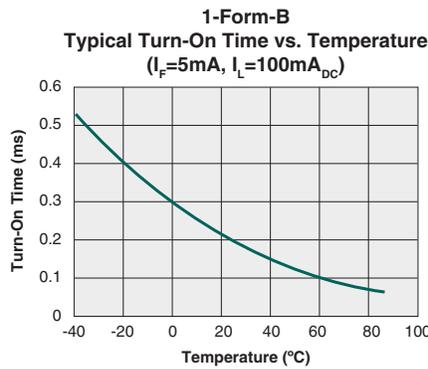
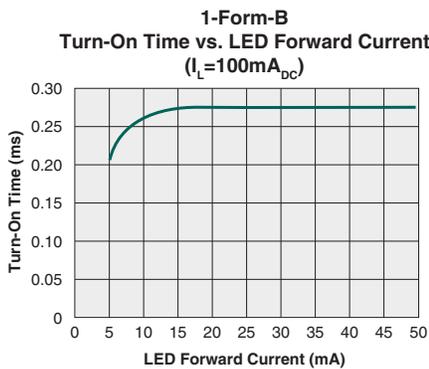
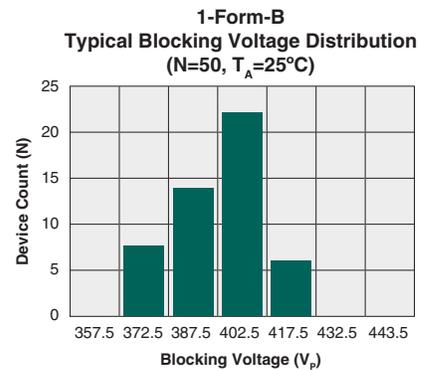
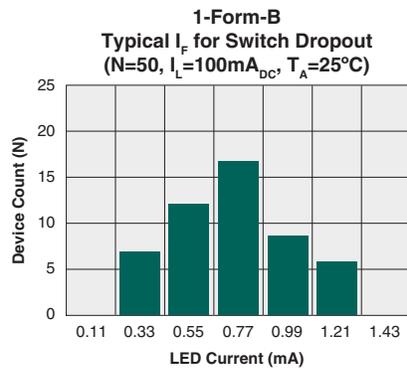
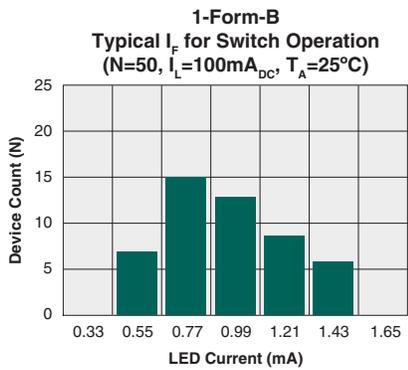
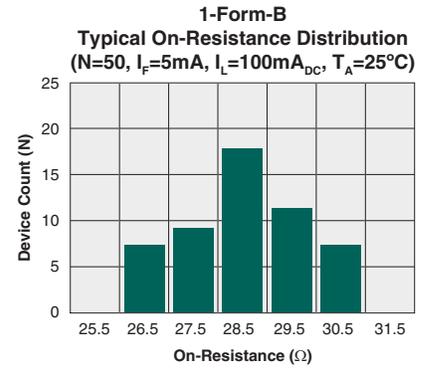
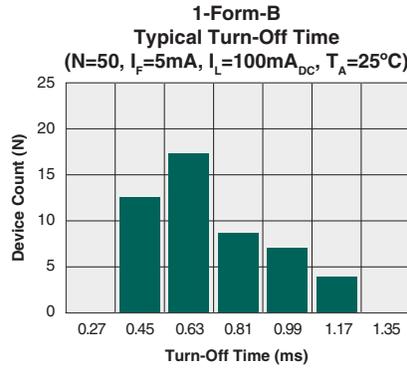
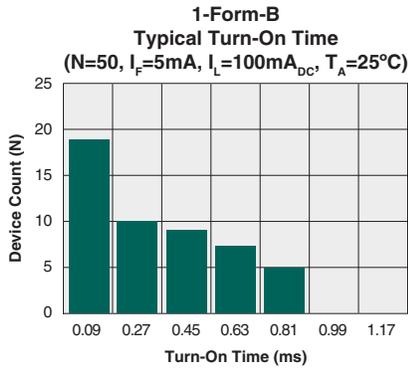
* The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

1-FORM-A RELAY PERFORMANCE DATA (cont.)*



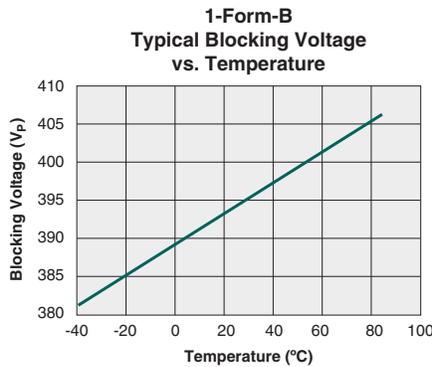
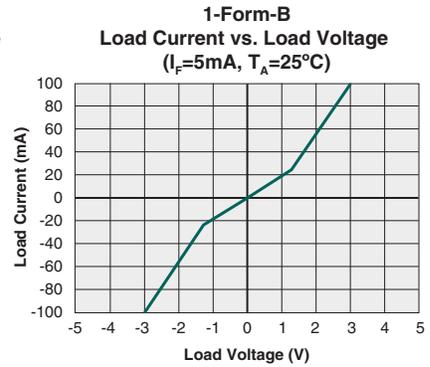
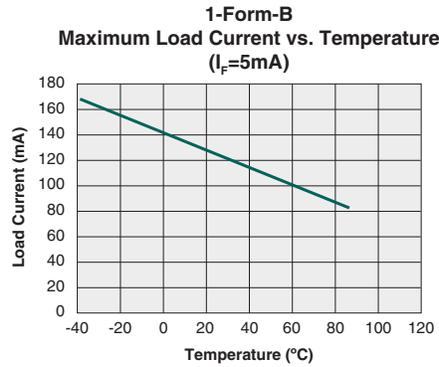
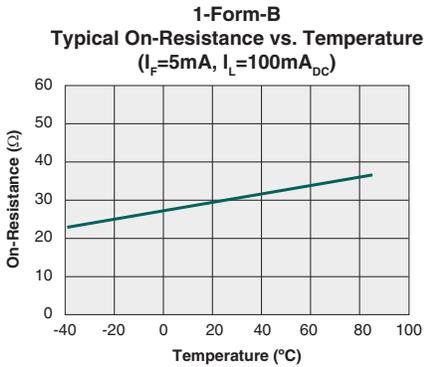
* The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

1-FORM-B RELAY PERFORMANCE DATA*

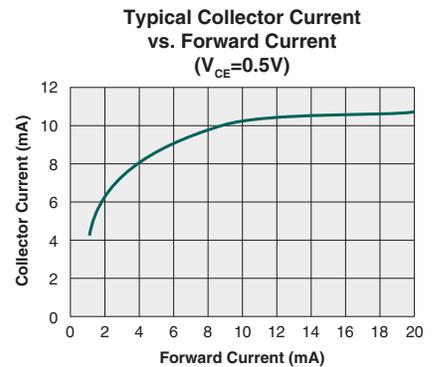
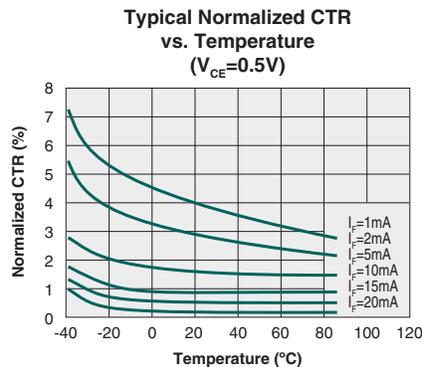
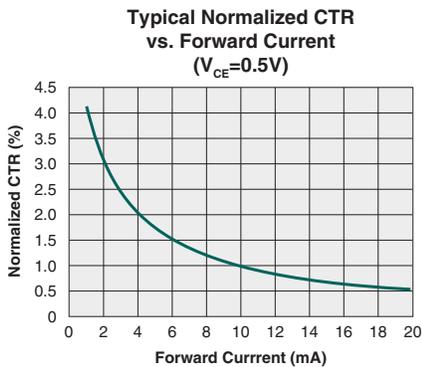


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1-FORM-B RELAY PERFORMANCE DATA (cont.)*



DETECTOR PERFORMANCE DATA*



* The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
IAB110P	MSL 1

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
IAB110P	260°C for 30 seconds

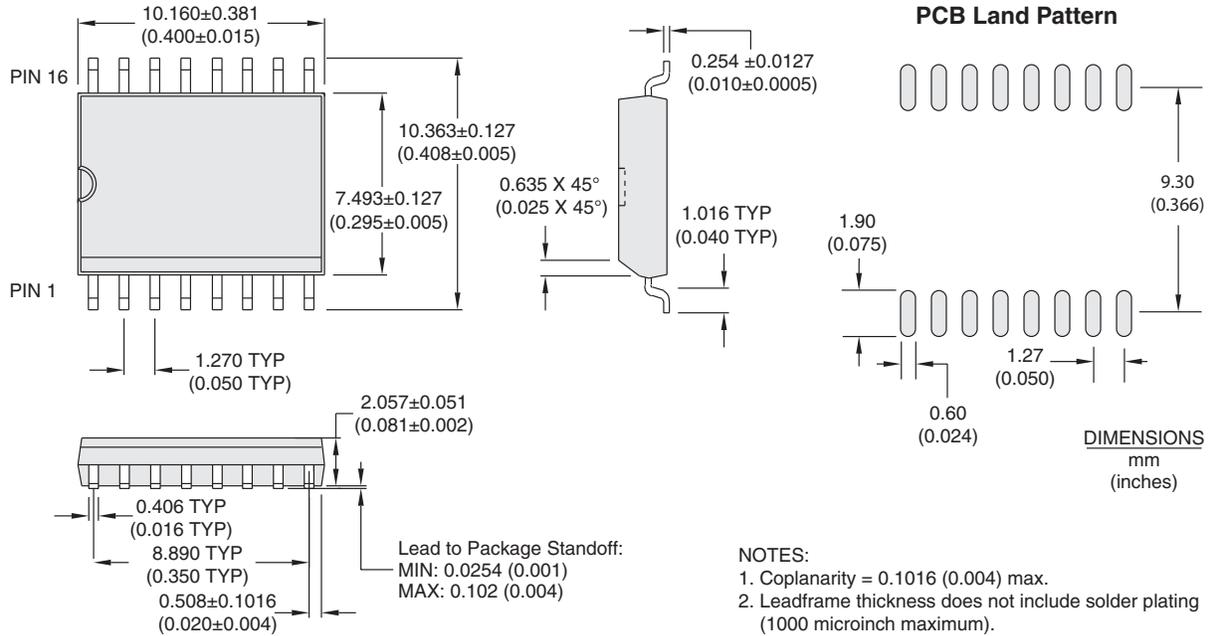
Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

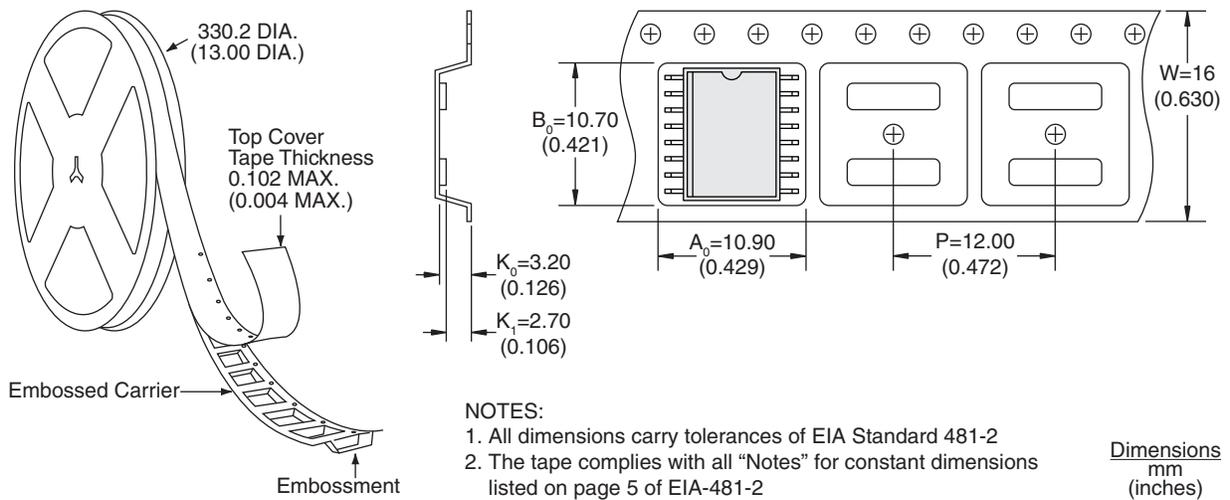


MECHANICAL DIMENSIONS

IAB110P



IAB110PTR Tape & Reel



For additional information please visit our website at: www.ixysic.com

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